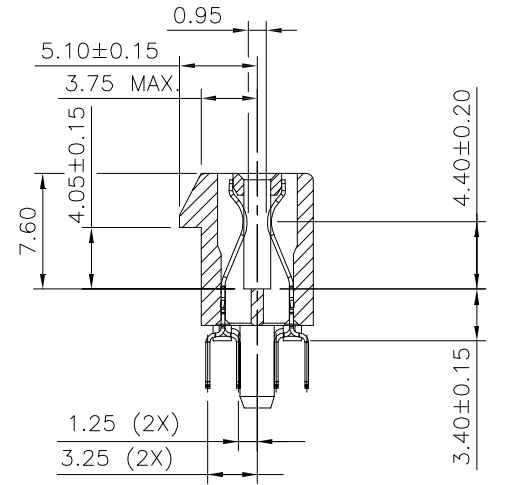
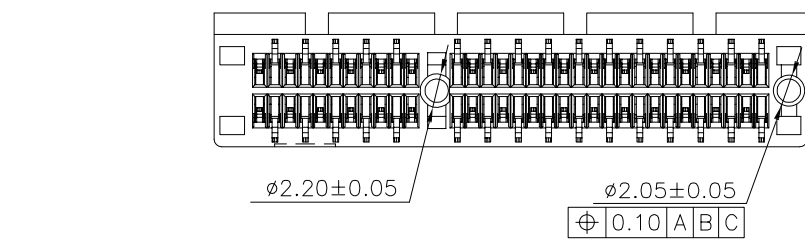
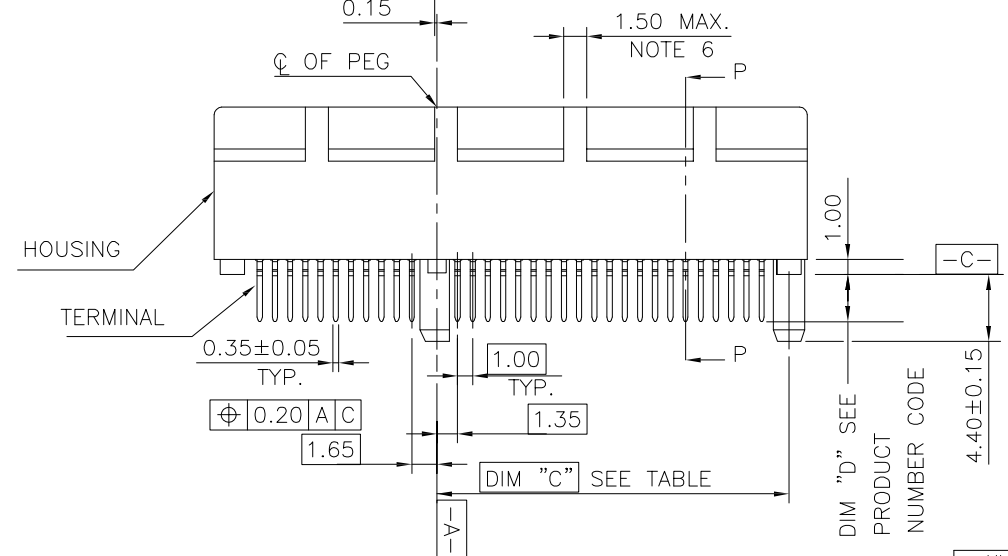
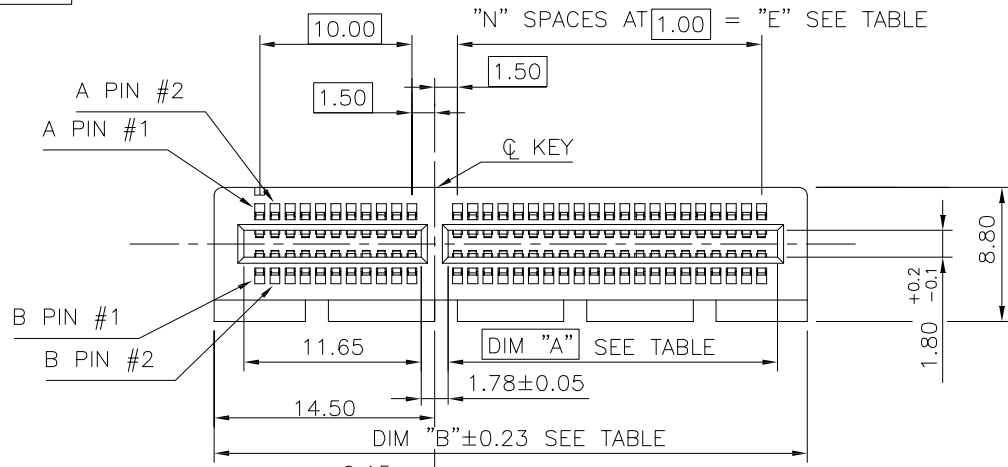
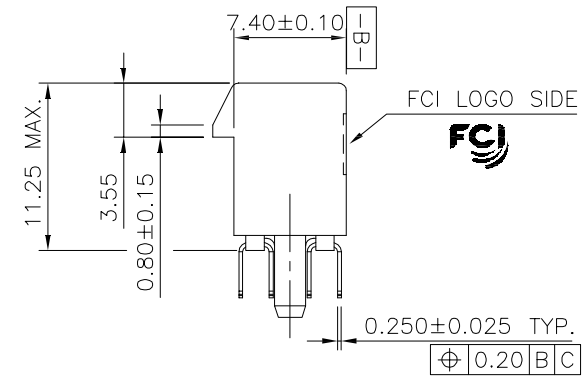


PRODUCT NO.
10108777-X0XXXX



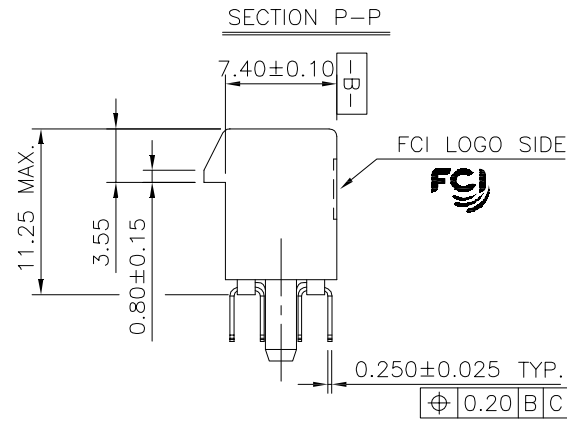
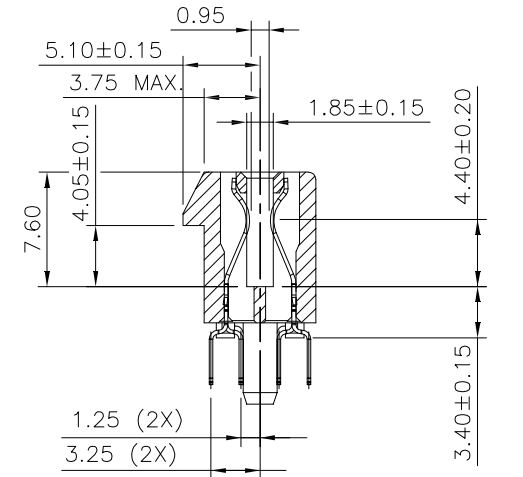
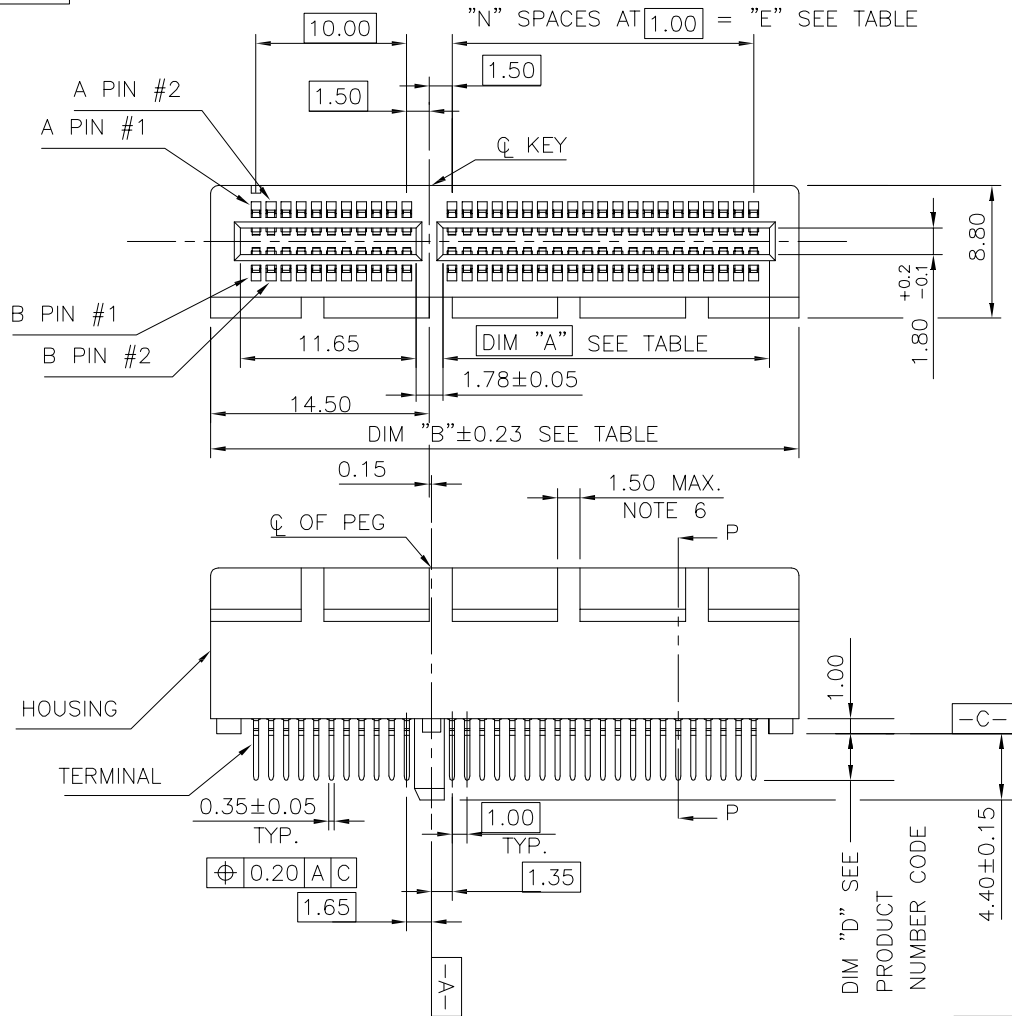
SECTION P-P



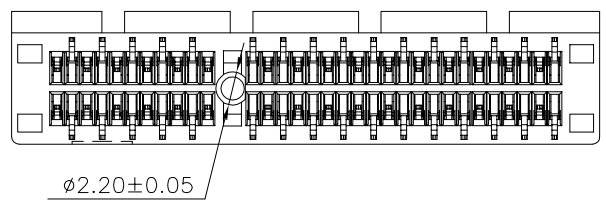
TWIN PLASTIC PEG TYPE

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5		MM		PCI_EXPRESS	
lfr		ecn no		dr		date		title	
A		T09-1162		J H		10/29/09		PCI_EXPRESS_CARD_EDGE_GEN3	
B		T-004920		J H		6/8/11		TH_ASS'Y	
C		DG-011582		HT		5/10/12		dwg no	
D		ELX-DG-013209		WL		07/24/12		sheet 1 of 7	
E		ELX-DG-2181-1		ST		05/27/15		size	
F		ELX-DG-24164		ZH		05/30/16		10108777	
sheet index		revision sheet		F		7		CUSTOMER Drawing	

PRODUCT NO.
10108777-X2XXXX

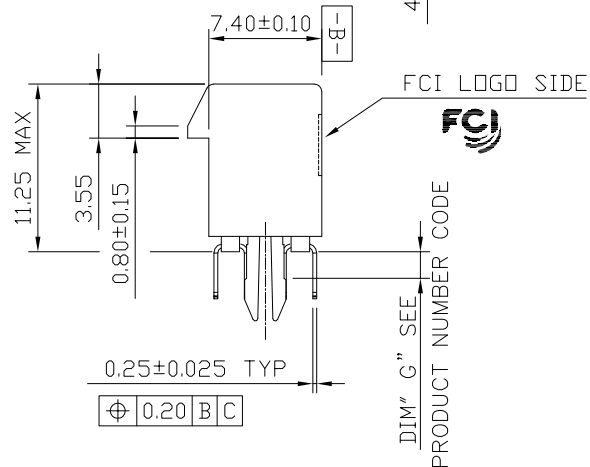
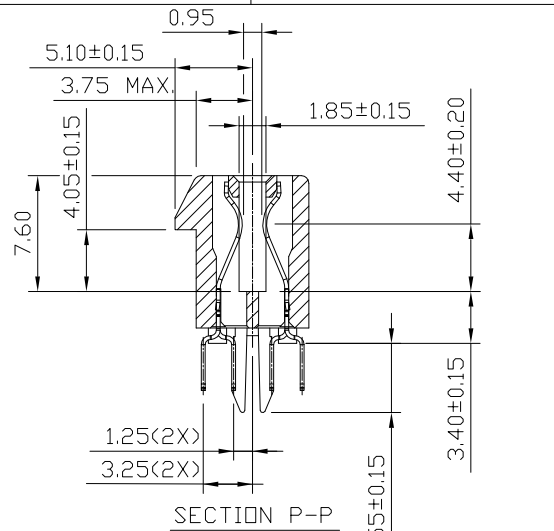
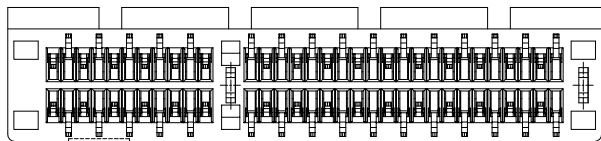
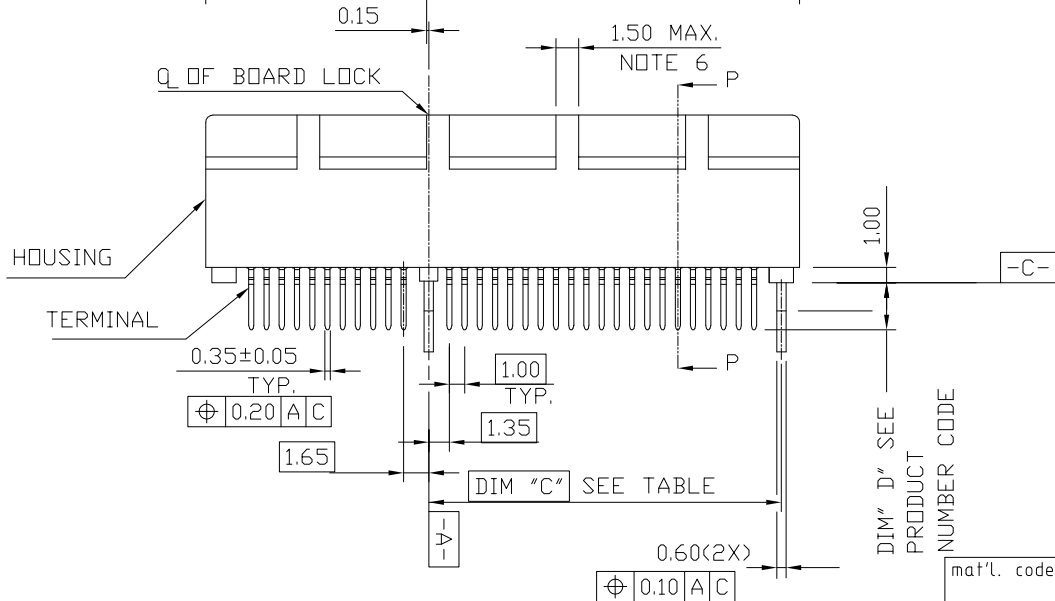
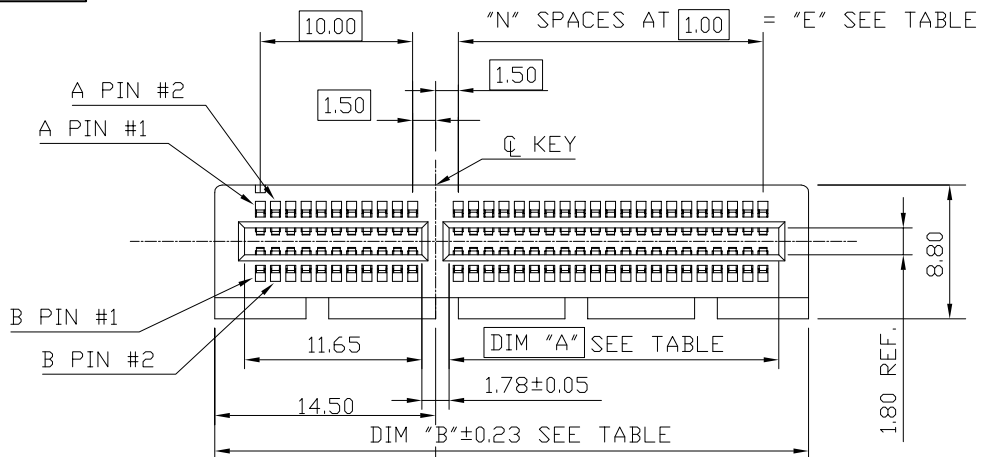


SINGLE PLASTIC PEG TYPE



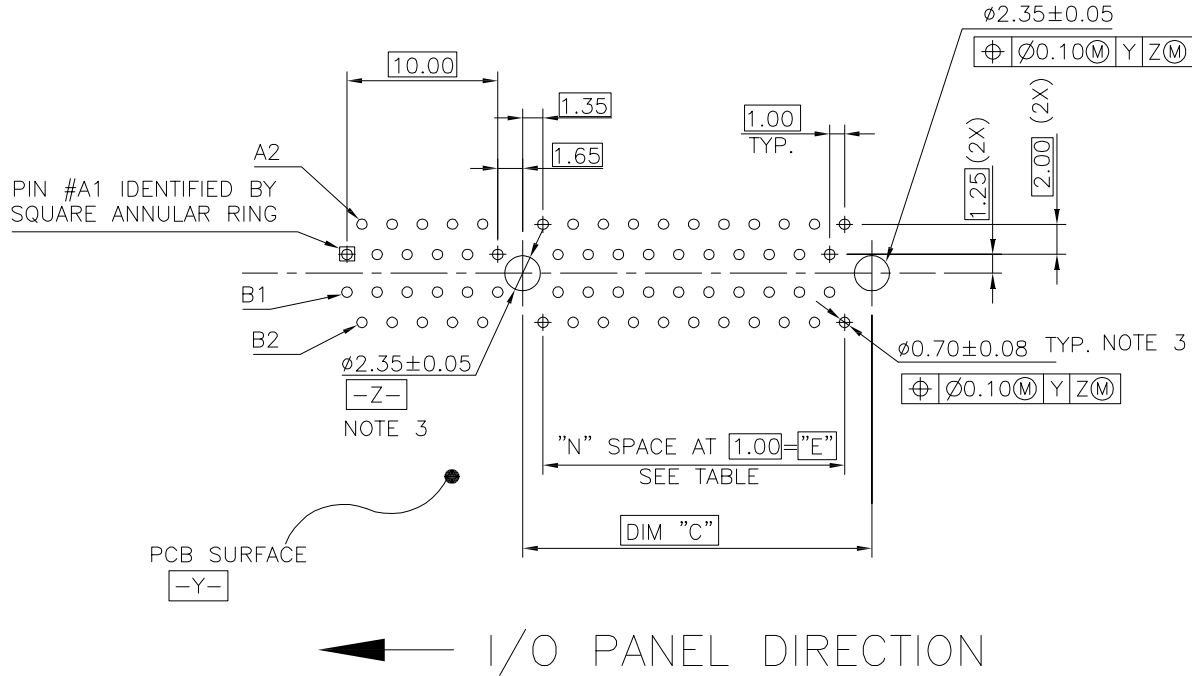
mat'l. code		-		surface		✓ tolerance ASME_Y14.5		projection		product family	
lfr		ecn no		dr		date		tolerances unless otherwise specified		PCI_EXPRESS	
								angles		title	
								±2'		PCI_EXPRESS_CARD_EDGE_GEN3 TH_ASS'Y	
								LineG		dwg no	
								.02±0.30		sheet 2 of 7	
								.00±0.20		size	
								.000±0.10		A4	
								scale N/A		10108777	
								dr ZHENHUA_LIU		2016-03-30	
								enfr ZHENHUA_LIU		2016-03-30	
								chr STONE_LI		2016-03-30	
								appd PM_ZHENG		2016-03-30	
sheet index		revision sheet		F 7				Amphenol FCI		type CUSTOMER Drawing	

PRODUCT NO.
10108777-X1XXXX



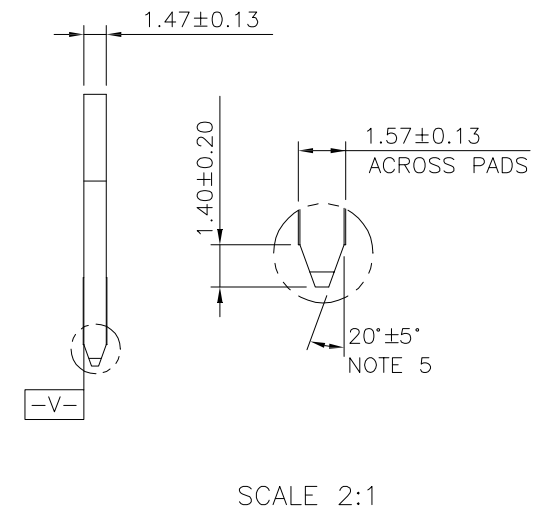
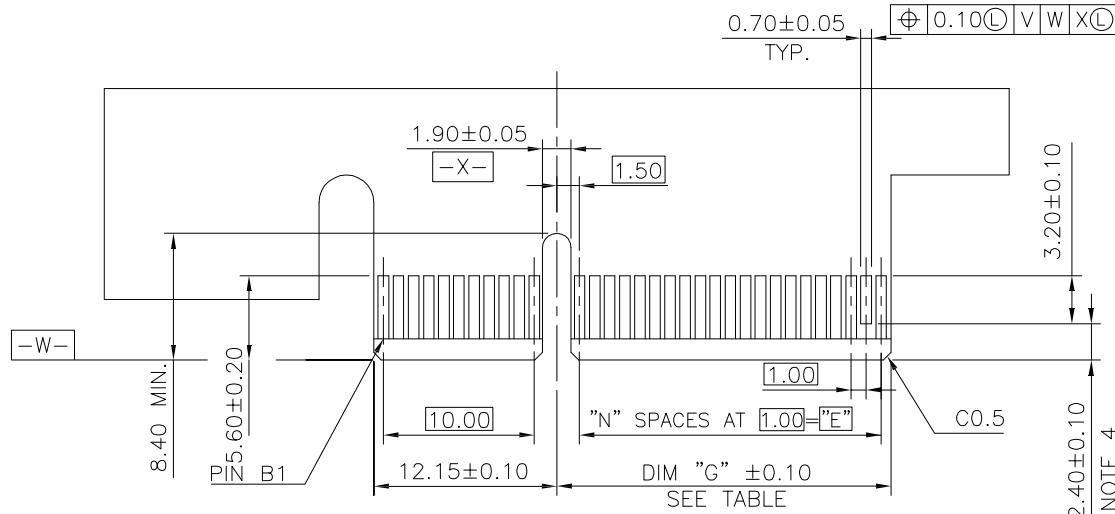
METAL BOARD LOCKS

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5				PCI_EXPRESS	
lfr		ecn no		dr		date		title	
								PCI_EXPRESS_CARD_EDGE_GEN3	
								TH_ASS'Y	
								sheet 3 of 7	
								size	
								A4	
								dwg no	
								10108777	
								type	
								CUSTOMER Drawing	
sheet index		revision sheet		F		7			

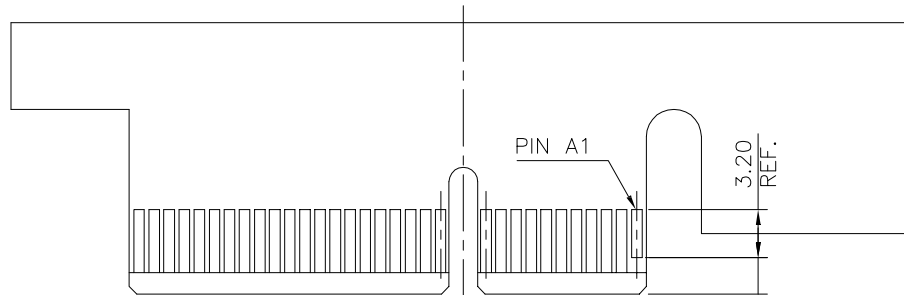


RECOMMENDED FOOTPRINT

mat'l. code		-		surface		- ✓		tolerance		ASME_Y14.5		projection		product family		PCI_EXPRESS	
lfr		ecn no		dr		date		tolerances unless otherwise specified		MM		title		PCI_EXPRESS_CARD_EDGE_GEN3		TH_ASS'Y	
								angles		.0±.0.20		scale N/A		dwg no		sheet 4 of 7 size	
								±2'		.000±.0.05		Amphenol FCI		10108777		A4	
				dr		ZHENHUA_LIU		2016-03-30						type		CUSTOMER Drawing	
				enfr		ZHENHUA_LIU		2016-03-30									
				chr		STONE_LI		2016-03-30									
				appd		PM_ZHENG		2016-03-30									
sheet index		revision sheet		F		7											



← I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE



I/O PANEL DIRECTION →
SECONDARY (SOLDER) SIDE

PIN "F" SEE TABLE 2.40 ± 0.10 NOTE 4

PIN "F" SEE TABLE 2.40 ± 0.10 NOTE 4

#	POS REF.	N	DIM "G"	"F"
36		6	8.15	B17
64		20	22.15	B31
98		37	39.15	B48
164		70	72.15	B81

ADD-IN CARD EDGE-FINGER DIMENSIONS

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5		MM		PCI_EXPRESS	
lfr		ecn no		dr		date		title	
								PCI_EXPRESS_CARD_EDGE_GEN3	
								TH_ASS'Y	
								dwg no	
								sheet 5 of 7	
								size	
								A4	
								type	
								CUSTOMER Drawing	
sheet index		revision sheet		F					
		7							

NOTES:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE NYLON, GLASS FILLED UL94V-0 RATED.
TERMINAL: COPPER ALLOY.

PLATING: 50u" NICKEL UNDERPLATE ALL OVER
CONTACT AREA PLATING - SEE PRODUCT NUMBER CODE
SOLDER TAIL: TIN OR TIN /LEAD(90/10)- SEE PRODUCT NUMBER CODE 100u" MIN. OVER 50u" NICKEL.

METAL BOARD LOCKS: COPPER ALLOY.
FINISH: 100u" TIN OR TIN/LEAD(90/10) OVER 50u" NICKEL
UNDERPLATE SEE PRODUCT NUMBER CODE.

2.PRODUCT SPECIFICATION: GS-12-233.

③THE HORIZONTAL AXIS FOR THE HOLE PATTERN IS ESTABLISHED BY

A LINE THROUGH THE CENTER OF THE TWO Ø2.35 HOLES.
THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM Z.

④NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND PIN NUMBERS "F".

⑤CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

⑥FREQUENCY & LOCATION AT SUPPLIER DISCRETION. RIDGE MAY BE CONTINUOUS WITH NO BREAKS.

7.RoHS COMPATIBLE PRODUCT SPECIFICATIONS:

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY:

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C TEMPERATURE FOR 10 SECONDS IN RE-FLOW APPLICATION, SEE NOTE 8 FOR APPLICATION.

PRODUCT NUMBER CODE

10108777 -x x x x x x □ □

LEAD FREE OPTION

LEAVE BLANK FOR TERMINAL PLATING 3,4,5
"LF" FOR TERMINAL PLATING OPTION 0,1,2

PACKAGING OPTIONS

- △ E-HARD TRAY WITH MYLAR FOR VACUUM PACKAGING (FOR 164P ONLY)
- T-SOFT TRAY PACKAGING
- M-SOFT TRAY PACKAGING & MYLAR TAPE. SEE FIGURE 1
- Y-HARD TRAY PACKAGING (FOR 36P,98P AND 164P ONLY)
- △ F Z-HARD TRAY PACKAGING WITH MYLAR (FOR 36P,98P AND 164P ONLY)
- R-TAPE & REEL PACKAGING WITHOUT MYLAR (FOR 34, 64, 98P ONLY)
- W-TAPE & REEL PACKAGING WITHOUT MYLAR (FOR 98P ONLY), WITH 18.0MM CAVITY WIDTH
- A-TAPE & REEL PACKAGING WITH MYLAR (FOR 36, 64, 98P ONLY)

POS OPTIONS

- 0-36
- 1-64
- 2-98
- 3-164

TAIL LENGTH OPTIONS

CONNECTOR	# POS REF.	N	DIM "A"	DIM "B"	DIM "C"	"E"
1 PORT	36	6	7.65	25.00	9.15	6.00
4 PORT	64	20	21.65	39.00	23.15	20.00
8 PORT	98	37	38.65	56.00	40.15	37.00
16 PORT	164	70	71.65	89.00	73.15	70.00

- 8.AN ADEQUATE PROCEDURE SET FORTH IN THE FOLLOWING ENSURE THAT THE PRODUCT RELIABILITY CAN BE ACHIEVED DURING AND AFTER PCB ASSEMBLY OPERATION.
- 8.1IF PARTIAL LOT ARE USED, THE REMAINING CONNECTORS MUST BE RESEALED AND PLACED IN SAFE STORAGE WITHIN SIX HOURS OF BAG OPENING.
- 8.2THE SAFE STORAGE CONDITION IS RECOMMENDED AT 25°C, 40%RH.
- 8.3NOT FOLLOWING THE PROCEDURE MAY CAUSE BLISTER DAMAGE DURING RE-FLOW PROCESS.
- 8.4IF BAKING IS REQUIRED, CONNECTOR SHALL BE BAKED FOR 4 HOURS AT 125°C.
- 8.5REFERENCE SPECIFICATION: IPC/JEDEC J-STD-033A.

HOUSING COLOR OPTIONS

- 0-NATURAL
- 1-BLACK

PEGS OPTIONS

- 0-PLASTIC PEGS, DIM
- 1-METAL BOARD LOCKS
- 2-SINGLE PLASTIC PEGS

TERMINAL PLATING OPTIONS

- 0-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS
- 1-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS
- 2-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN TAIL AREA ----- COMPATIBLE RoHS
- 3-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA ----- INCOMPLIANT RoHS
- 4-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA ----- INCOMPLIANT RoHS
- 5-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN/LEAD TAIL AREA ----- INCOMPLIANT RoHS

	DIM "D"	PCB THICKNESS	BOARD LOCKS DIM "G"
0	2.30 ^{+0.25} / _{-0.13}	1.56±0.10	1.70±0.15
1	3.10 ^{+0.25} / _{-0.13}	2.36±0.10	2.50±0.15
2	2.54±0.25	1.56±0.10	1.70±0.15
3	1.90±0.25	1.56±0.10	1.70±0.15
4	3.10 ^{+0.25} / _{-0.13}	2.0±0.10	1.70±0.15

mat'l. code		surface		tolerance		projection		product family	
-		-		ASME_Y14.5				PCI_EXPRESS	
lfr		ecn no		dr		date		title	
								PCI_EXPRESS_CARD_EDGE_GEN3	
								TH_ASS'Y	
								dwg no	
								sheet 6 of 7	
								size	
								A4	
								type	
								CUSTOMER Drawing	
sheet		revision		F					
index		sheet		7					

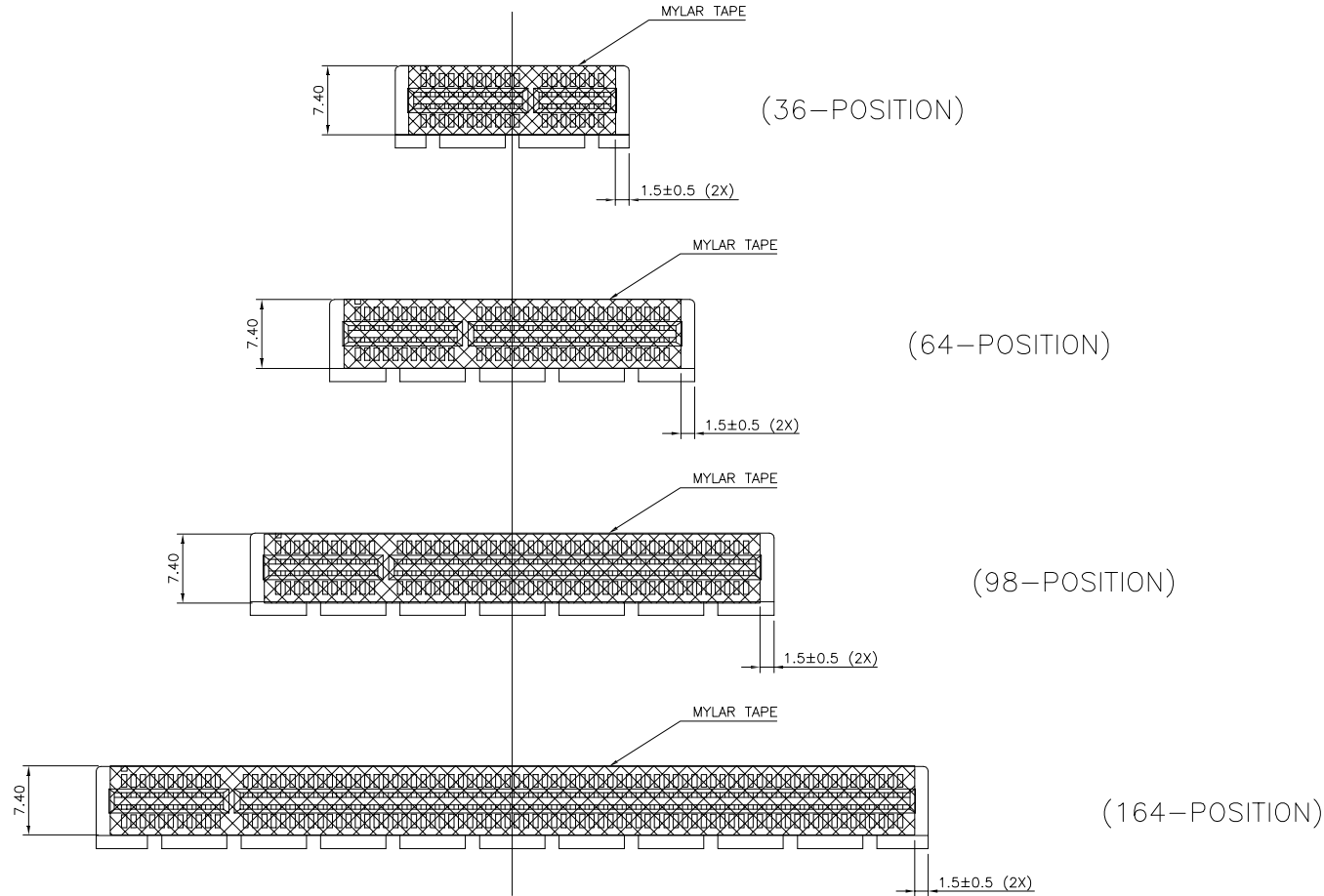


FIGURE 1

mat'l. code		-		surface	-	tolerance	ASME_Y14.5	projection	product family	PCI_EXPRESS		
lfr	ecn no	dr	date	tolerances unless otherwise specified				 MM	title			
				angles	±2'	lineal	.02±0.30		PCI_EXPRESS_CARD_EDGE_GEN3 TH_ASS'Y			
							.00±0.20	scale	N/A			
				dr	ZHENHUA_LIU	2016-03-30	.000±0.10			dwg no		
				enfr	ZHENHUA_LIU	2016-03-30	sheet 7 of 7			size		
				chr	STONE_LI	2016-03-30	10108777			A4		
				appd	PM_ZHENG	2016-03-30	CUSTOMER Drawing					
sheet index	revision sheet	F 7										